

EDITORIAL CALENDAR

	FEB / MAR	APR / MAY	JUN / JUL
	Issue date: Mar 15 Materials: Mar 8	Issue date: Apr 25 Materials: Apr 18	Issue date: Jun 9 Materials: Jun 1
	Booking: Mar 1 Editorial: Feb 15	Booking: Apr 10 Editorial: Mar 30	Booking: May 25 Editorial: May 11
Cover Story	Metrology/Test & Measurement	Materials	3D Integration/Heterogeneous Integration
Tech Features	Advanced Packaging	Lithography	IC Design / Software / Tool
Column	Silicon Photonics Platforms/ PICs	Advanced Process Equipment / Advanced Process Control	Wafer handling / Inspection / Cleaning
Special Supplements	AI, IoT, 5G Applications	Power Electronics	IP, Chiplets, SoC, SiP, PoP ...

	AUG / SEP	OCT / NOV	DEC / JAN
	Issue date: Aug 18 Materials: Aug 11	Issue date: Oct 25 Materials: Oct 18	Issue date: Dec 22 Materials: Dec 15
	Booking: Aug 4 Editorial: Jul 20	Booking: Oct 11 Editorial: Sep 27	Booking: Dec 8 Editorial: Nov 24
Cover Story	Smart Manufacturing / Data Tools/MES	ALD / ALE Deposition / Etch	Packaging & Assembly
Tech Features	MEMS / Sensors	Materials	Back-end processing
Column	Memory	OLED / Displays	Automation / Facility / Cleanroom
Special Supplements	Supply Chain / Local Supply / Sustainability	Autonomous Vehicle / Electric Vehicle	Critical Subsystems

	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
eFOCUS CALENDAR	12 31	9 23	9 30 16	13 27	11 25	8 29 16	13 27	10 31 17	14 28	12 26	9 30 16	14 28
RESOURCE CENTER SCHEDULE												

Bonus Distribution

FEB / MAR

- XMIPE, 4/21-23

APR / MAY

- SENSOR EXPO 2023 Shenzhen, 5/16-18
- SNEC International PV Power Expo, Shanghai, 5/24-26

JUN / JUL

- EDICON China, Beijing, 5/26
- Chip China/ STCon, Suzhou, June
- Embedded World China, Shanghai, 6/14-16
- SEMICON China, Shanghai, 6/29-7/1
- SEMICON West, San Francisco, 7/11-13
- Nepcon China/ EMT China, Shanghai, 7/19-21

AUG / SEP

- Power China 2023, Guangzhou, 8/8-10
- CIOE, Shenzhen, 9/6-8
- SEMICON Taiwan, Taipei, 9/6-8

OCT / NOV

- Nepcon Asia, Shenzhen, 10/11-13